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(54) COMPOSITION FOR FOAMED HOT-MELT ADHESIVE

(57)Abstract:

PURPOSE: To provide the titled compsn. with stable foamability, showing effective sealing performance when applied to rough surfaces, by incorporating a surface-active fluorine compd. (or an organosilicon compd.) with a thermoplastic resin.

CONSTITUTION: 100pts.wt. thermoplastic resin which melts at 70W250° C and becomes fluid, selected from an addn. polymer [e.g., ethylene (co) polymer, acrylic resin] and an ester-type condensation polymer (e.g, polyester prepared by condensation of an acid component consisting mainly of terephthalic acid and a diol component such as ethylene glycol) is mixed with about 0.001W5pts.wt. surface- active fluorine compd. (e.g., perfluoroalkylethylene oxide adduct) and/or organosilicon compd. (e.g., dimethylpolysiloxane/polyethylene oxide copolymer) under heating and melted to form a compsn. for foamed hot-melt adhesives.

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